

## XFLO® Micro FF

Low Profile, High Compressive Strength UFH Floorboards with Conductive Facing



### Product Information

XFLO® Micro FF low profile routed under floor heating insulation boards have an ultra high compressive strength and aluminium foil facing for added thermal diffusion. Once covered with **ScreedBoard®** or a floor decking, they provide an effective solution to limited height underfloor heating application.

### Product Benefits

- Low profile, as thin as 15mm
- Aluminum foil facing for improved heat diffusion
- Ultra high compressive strength - 500kPa
- Manufactured to suit pipe and centres required
- Easy to cut to size and install

### Technical Data

		XFLO® Micro FF
Product description	-	Aluminum foil faced, low profile, ultra high compressive strength UFH board
Strength at 10% compression	kPa	500
Thermal conductivity	W/mK	0.035
Temperature range	°C	-50/+75
Route sizes available (to suit pipe diameter)	mm	10, 12, 15, 16
Pipe centres	mm	150
Board size	mm	600 x 1200
Thickness'	mm	15, 18, 20, 25

### Third Party Accreditation and Approvals



### Environmental Credentials

